

*CLAIM AMENDMENTS*

1. (Currently Amended) A high-frequency power amplifier comprising:  
a multilayer substrate ~~formed by laminating~~ including a plurality of laminated dielectric layers;  
a wiring prohibited area ~~provided~~ located on at least one of ~~a~~ an obverse side and a reverse side of said multilayer substrate in which wiring is prohibited;  
a first strip conductor ~~provided~~ located within said multilayer substrate;  
a second strip conductor ~~provided such that it is located at a position, in a lamination direction of said multilayer substrate is,~~ different from that of said first strip conductor;  
a via ~~for~~ electrically connecting said first strip conductor ~~and to~~ said second strip conductor; and  
a first grounding conductor and a second grounding conductor disposed sequentially in ~~said the~~ lamination direction of said multilayer substrate and sandwiching said first strip conductor and said second strip conductor~~s~~, wherein at least one of said first grounding conductor and said second grounding conductor includes:  
a first grounding conductor portion ~~provided~~ for said wiring prohibited area; and  
a second grounding conductor portion ~~provided~~ for an area other than said wiring prohibited area ~~such so that a position of~~ said second grounding conductor portion is positioned, in ~~said the~~ lamination direction of said multilayer substrate ~~is,~~ different from ~~that of~~ said first grounding conductor portion.
2. (Currently Amended) The high-frequency power amplifier according to claim 1, wherein said wiring prohibited area includes:  
a first wiring prohibited area ~~provided~~ located on ~~said the~~ obverse side of said multilayer substrate; and  
a second wiring prohibited area ~~provided~~ located on ~~said the~~ reverse side of said multilayer substrate ~~such that, said second wiring prohibited area is disposed at a position at which it overlaps~~ overlapping said first wiring prohibited area ~~as, when viewed in~~ the lamination direction of said multilayer substrate~~s~~, wherein a length of said first wiring prohibited area in said lamination direction of said multilayer substrate is different from that of said second wiring prohibited area.

3. (Currently Amended) The high-frequency power amplifier according to claim 1, wherein said wiring prohibited area includes:

a first wiring prohibited area ~~provided located~~ on ~~said~~ ~~the~~ obverse side of said multilayer substrate; and

a second wiring prohibited area ~~provided located~~ on ~~said~~ ~~the~~ reverse side of said multilayer substrate ~~such that~~, said second wiring prohibited area ~~is disposed at a position at which it does not overlap~~ overlapping said first wiring prohibited area ~~as, when viewed in~~ ~~said~~ ~~the~~ lamination direction of said multilayer substrate.

4. (Currently Amended) The high-frequency power amplifier according to claim 1, wherein one end of said first grounding conductor portion ~~is formed such that it runs along a periphery of said via as, when viewed in~~ ~~said~~ ~~the~~ lamination direction of said multilayer substrate.

5. (Currently Amended) A high-frequency power amplifier comprising:

a multilayer substrate ~~formed by laminating~~ ~~including~~ a plurality of laminated dielectric layers;

a first wiring prohibited area ~~provided located~~ on ~~a~~ ~~an~~ obverse side of said multilayer substrate;

a second wiring prohibited area ~~provided located~~ on a reverse side of said multilayer substrate ~~such that~~, said second wiring prohibited area ~~is disposed at a position at which it overlaps~~ overlapping said first wiring prohibited area ~~as, when viewed in a lamination direction of said multilayer substrate;~~

a strip conductor disposed within said multilayer substrate; and

a first grounding conductor and a second grounding conductor disposed sequentially in ~~said~~ ~~the~~ lamination direction of said multilayer substrate and sandwiching said strip conductor, wherein a

length of said first wiring prohibited area in ~~said~~ ~~the~~ lamination direction of said multilayer substrate is equal to that of said second wiring prohibited area, and  
~~wherein~~ said first grounding conductor includes:

a first grounding conductor portion ~~provided~~ for said first wiring prohibited area; and

a second grounding conductor portion ~~provided~~ for an area on ~~said~~ ~~the~~ obverse side of said multilayer substrate such that ~~a position of~~ said second grounding conductor portion is positioned, in ~~said~~ ~~the~~ lamination direction of said multilayer

substrate ~~is~~, different from ~~that of~~ said first grounding conductor portion, said the area being other than outside said first wiring prohibited area; and

~~wherein~~ said second grounding conductor includes:

a third grounding conductor portion ~~provided~~ for said second wiring prohibited area; and

a fourth grounding conductor portion ~~provided~~ for an area on ~~said the~~ reverse side of said multilayer substrate such that ~~a position of~~ said fourth grounding conductor portion is positioned, in ~~said the~~ lamination direction of said multilayer substrate ~~is~~, different from ~~that of~~ said third grounding conductor portion, said the area being other than outside said second wiring prohibited area.